



SCALE 2:1

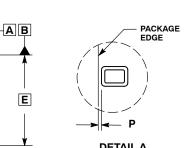
52X

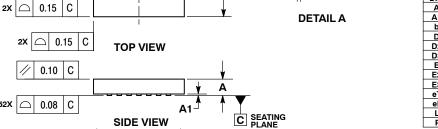
PIN ONE -REFERENCE

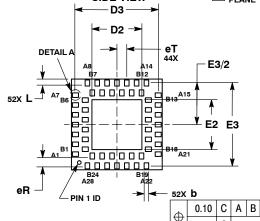


D

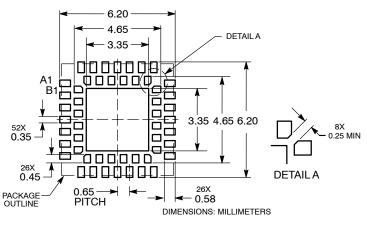
DATE 29 MAR 2016







BOTTOM VIEW SOLDERING FOOTPRINT



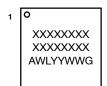
0.05

C NOTE 3

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 CONTROLLING DIMENSIONS: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.80	0.90	1.00	
A1	0.00	0.05	0.10	
b	0.15	0.20	0.25	
D	6.00 BSC			
D2	3.20	3.30	3.40	
D3	5.50 BSC			
E	6.00 BSC			
E2	3.20	3.30	3.40	
E3	5.50 BSC			
eT	0.65 BSC			
eR	0.65 BSC			
L	0.35	0.40	0.45	
Р	0.05 REF			

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location Α

WL = Wafer Lot YY = Year

WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	QFN52 6x6, 0.65P		PAGE 1 OF 1

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